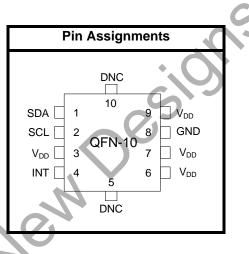


# UV INDEX AND AMBIENT LIGHT SENSOR IC WITH I<sup>2</sup>C INTERFACE

#### Features

- Integrated UV index sensor
  - Digital UV Index register that can be read through I<sup>2</sup>C interface
  - Factory calibration to address part-to-part variation
- Integrated ambient light sensor
  - 100 mlx resolution possible, allowing operation under dark glass
  - 1 to 128 klx dynamic range possible across two ADC range settings
  - Accurate lux measurements with IR correction algorithm

- Industry's lowest power consumption
  - 1.71 to 3.6 V supply voltage
  - < 500 nA standby current</p>
  - Internal and external wake support
  - Built-in voltage supply monitor and power-on reset controller
- I<sup>2</sup>C Serial communications
  - Up to 3.4 Mbps data rate
  - Slave mode hardware address decoding
- Small-outline 10-lead 2x2 mm QFN
- Temperature Range
  - -40 to +85 °C



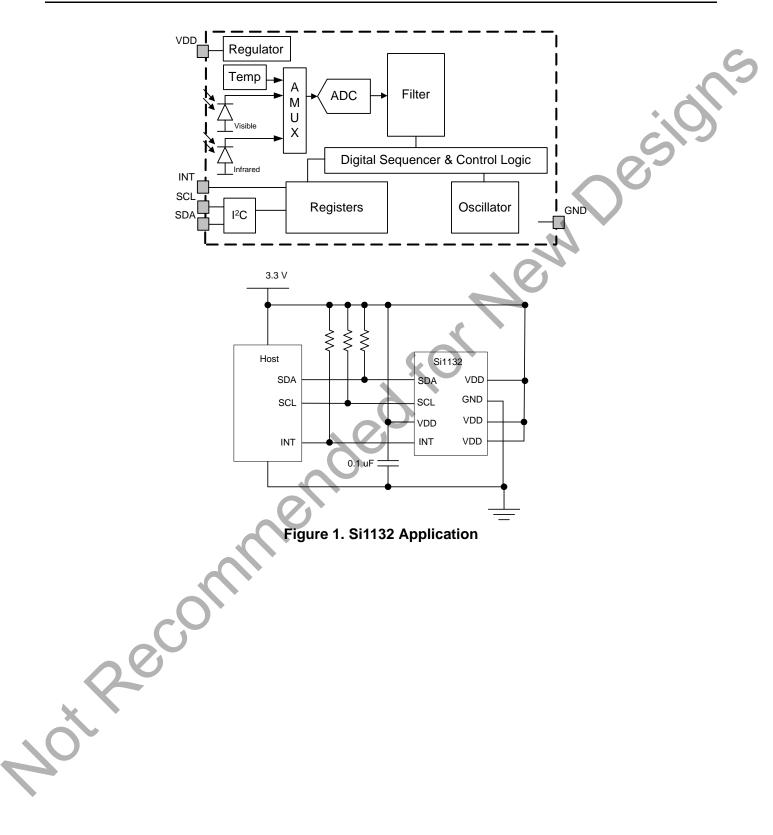
#### Applications

- Fitness/health electronics
- Smart watches
- Smartphone handsets
- Tablets
- Portable consumer electronics
- Display-backlighting control

#### Description

The Si1132 is a low-power, ultraviolet (UV) index, and ambient light sensor with  $I^2C$  digital interface and programmable-event interrupt output. This sensor IC includes an analog-to-digital converter, integrated high-sensitivity visible and infrared photodiodes, and digital signal processor. The Si1132 offers excellent performance under a wide dynamic range and a variety of light sources including direct sunlight. The Si1132 can also work under dark glass covers. The photodiode response and associated digital conversion circuitry provide excellent immunity to artificial light flicker noise and natural light flutter noise. The Si1132 devices are provided in a 10-lead 2x2 mm QFN package and are capable of operation from 1.71 to 3.6 V over the -40 to +85 °C temperature range.

## **Functional Block Diagram**





# TABLE OF CONTENTS

1. Electrical Specifications
1.1. Performance Tables
1.2. Typical Performance Graphs
2. Functional Description
2.1. Introduction
2.2. Ambient Light
2.3. Ultraviolet (UV) Index
2.4. Host Interface
3. Operational Modes
3.1. Off Mode
3.2. Initialization Mode
3.3. Standby Mode
3.4. Forced Conversion Mode
3.5. Autonomous Operation Mode
4. Programming Guide
4.1. Command and Response Structure
4.2. Command Protocol
4.3. Resource Summary
4.4. Signal Path Software Model
4.5. I <sup>2</sup> C Registers
4.4. Signal Fail Software Model       23         4.5. I <sup>2</sup> C Registers       24         4.6. Parameter RAM       35         5. Pin Descriptions       42         6. Ordering Guide       43
5. Pin Descriptions
6. Ordering Guide
7. Package Outline: 10-Pin QFN
8. Suggested PCB Land Pattern
Document Change List
Contact Information
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# **1. Electrical Specifications**

## 1.1. Performance Tables

### **Table 1. Recommended Operating Conditions**

Parameter	Symbol	Test Condition	Min	Tun	Мах	Unit
Falameter	Symbol	Test condition	IVIIII	Тур	IVIAX	Unit
V <sub>DD</sub> Supply Voltage	$V_{DD}$		1.71	_	3.6 🔷	V
V <sub>DD</sub> OFF Supply Voltage	$V_{DD_OFF}$	OFF mode	-0.3		1.0	V
V <sub>DD</sub> Supply Ripple Voltage		V <sub>DD</sub> = 3.3 V 1 kHz–10 MHz			50	mVpp
Operating Temperature	Т		-40	25	85	°C
SCL, SDA, Input High Logic Voltage	I <sup>2</sup> C <sub>VIH</sub>		V <sub>DD</sub> x0.7	7	V <sub>DD</sub>	V
SCL, SDA Input Low Logic Voltage	$I^2 C_{VIL}$		0	_	V <sub>DD</sub> x0.3	V
Operation under Direct Sunlight	Edc	*	_	_	128	klx
Start-Up Time		V <sub>DD</sub> above 1.71 V	25	—		ms

## Table 2. Performance Characteristics<sup>1</sup>

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
I <sub>DD</sub> OFF Mode	I <sub>off</sub>	V <sub>DD</sub> < V <sub>DD_OFF</sub> (leakage from SCL, SDA, and INT not included)	_	240	1000	nA
I <sub>DD</sub> Standby Mode	I <sub>sb</sub>	No ALS Conversions No I <sup>2</sup> C Activity $V_{DD} = 1.8 V$	—	150	500	nA
I <sub>DD</sub> Standby Mode	I <sub>sb</sub>	No ALS Conversions No I <sup>2</sup> C Activity V <sub>DD</sub> =3.3 V		1.4		μA
I <sub>DD</sub> Actively Measuring	I <sub>active</sub>	V <sub>DD</sub> = 3.3 V	_	4.3	5.5	mA
INT, SCL, SDA Leakage Current		V <sub>DD</sub> = 3.3 V	-1	_	1	μA
Actively Measuring Time <sup>2</sup>		UV or ALS VIS + ALS IR	_	285		μs

Notes:

1.

Unless specifically stated in "Conditions", electrical data assumes ambient light levels < 1 klx. Represents the time during which the device is drawing a current equal to  $I_{active}$  for power estimation purposes. 2. Assumes default settings.



Table 2. Performance	Characteristics <sup>1</sup>	(Continued)
----------------------	------------------------------	-------------

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Visible Photodiode Response		Sunlight ALS_VIS_ADC_GAIN=0 VIS_RANGE=0	_	0.282	_	ADC counts/ lux
		2500K incandescent bulb ALS_VIS_ADC_GAIN=0 VIS_RANGE=0	_	0.319	C	ADC counts/ lux
		"Cool white" fluorescent ALS_VIS_ADC_GAIN=0 VIS_RANGE=0	_	0.146	G	ADC counts/ lux
		Infrared LED (875 nm) ALS_VIS_ADC_GAIN=0 VIS_RANGE=0	-	8.277	_	ADC counts. m <sup>2</sup> /W
Small Infrared Photodiode Response		Sunlight ALS_IR_ADC_GAIN=0 IR_RANGE=0	-	2.44	_	ADC counts/ lux
		2500K incandescent bulb ALS_IR_ADC_GAIN=0 IR_RANGE=0	_	8.46	_	ADC counts/ lux
		"Cool white" fluorescent ALS_IR_ADC_GAIN=0 IR_RANGE=0	_	0.71	_	ADC counts/ lux
		Infrared LED (875 nm) ALS_IR_ADC_GAIN=0 IR_RANGE=0	_	452.38	_	ADC counts. m <sup>2</sup> /W
Visible Photodiode Noise		All gain settings	_	7	_	ADC counts RMS
Small Infrared Photodiode Noise		All gain settings	_	1	_	ADC counts RMS

 Unless specifically stated in "Conditions", electrical data assumes ambient light levels < 1 klx.</li>
 Represents the time during which the device is drawing a current equal to I<sub>active</sub> for power estimation purposes. Assumes default settings.



## Table 2. Performance Characteristics<sup>1</sup> (Continued)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Visible Photodiode Offset		VIS_RANGE=0	_		_	ADC
Drift		ALS_VIS_ADC_GAIN=0		-0.3		counts/
		ALS_VIS_ADC_GAIN=1		-0.11		O°
		ALS_VIS_ADC_GAIN=2		-0.06		
		ALS_VIS_ADC_GAIN=3		-0.03		
		ALS_VIS_ADC_GAIN=4		-0.01	C	
		ALS_VIS_ADC_GAIN=5		-0.008	0	
		ALS_VIS_ADC_GAIN=6		-0.007	$\mathbf{O}$	
		ALS_VIS_ADC_GAIN=7		-0.008		
Small Infrared Photodiode		IR_RANGE=0	—		_	ADC
Offset Drift		IR_GAIN=0		-0.3		counts/
		IR_GAIN=1		-0.06		°C
		IR_GAIN=2	$\mathcal{O}_{1}$	-0.03		
		IR_GAIN=3		-0.01		
SCL, SDA, INT Output Low	V <sub>OL</sub>	I = 4 mA, V <sub>DD</sub> > 2.0 V	_		V <sub>DD</sub> x0.	V
Voltage	0L	$I = 4 \text{ mA}, V_{DD} < 2.0 \text{ V}$	_	_	2	V
					0.4	
Temperature Sensor Offset		25 °C		11136		ADC
						counts
Temperature Sensor Gain		~~~~		35		ADC
•						counts/
						°C
Notes:	ļļ		Į	ļ	ļ	Į

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 Unless specifically stated in "Conditions", electrical data assumes ambient light levels < 1 klx.</li>
 Represents the time during which the device is drawing a current equal to I<sub>active</sub> for power estimation purposes. Assumes default settings.



# Table 3. I<sup>2</sup>C Timing Specifications

Parameter	Symbol	Min	Тур	Max	Unit
Clock Frequency	f <sub>SCL</sub>	95	—	3400	kHz
Clock Pulse Width Low	t <sub>LOW</sub>	160		—	ns
Clock Pulse Width High	t <sub>ніGн</sub>	60	—	-	ns
Rise Time	t <sub>R</sub>	10	—	40	ns
Fall Time	t <sub>F</sub>	10	—	40	ns
Start Condition Hold Time	t <sub>HD.STA</sub>	160	-		ns
Start Condition Setup Time	t <sub>SU.STA</sub>	160	_	V-	ns
Input Data Setup Time	t <sub>SU.DAT</sub>	10	A		ns
Input Data Hold Time	t <sub>HD.DAT</sub>	0		—	ns
Stop Condition Setup Time	t <sub>SU.STO</sub>	160	/ _	—	ns

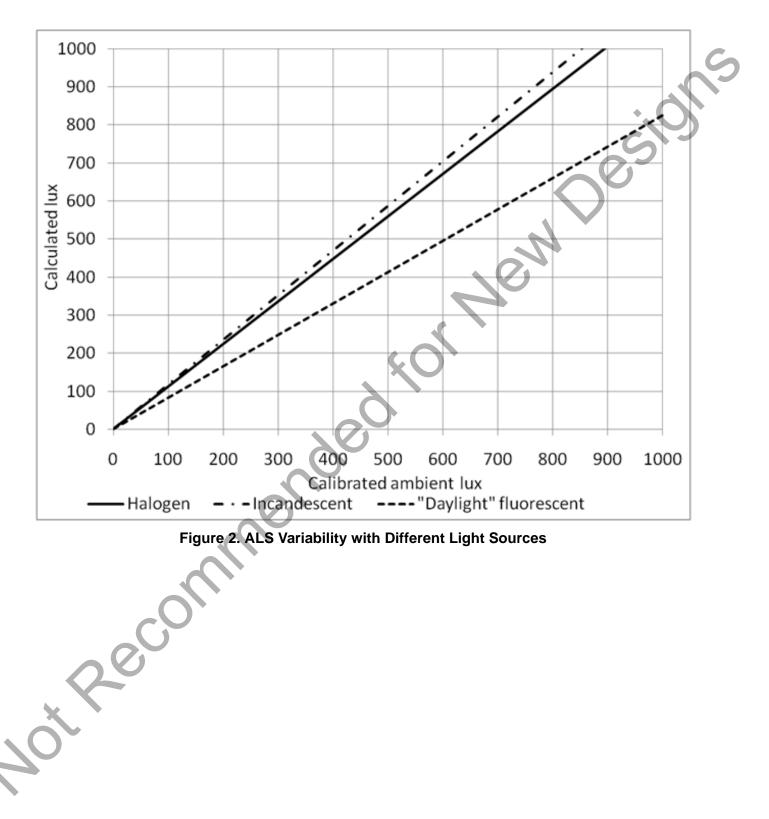
## Table 4. Absolute Maximum Limits

Parameter	Test Condition	Min	Тур	Max	Unit
V <sub>DD</sub> Supply Voltage		-0.3	—	4	V
Operating Temperature		-40	—	85	°C
Storage Temperature	XO	-65	—	85	°C
INT, SCL, SDA Voltage	at V <sub>DD</sub> = 0 V, T <sub>A</sub> < 85 °C	-0.5	_	3.6	V
ESD Rating	Human Body Model Machine Model	_	_	2 225	kV V
	Charged-Device Model	—		2	kV



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## **1.2. Typical Performance Graphs**





# 2. Functional Description

## 2.1. Introduction

The Si1132 is a UV index and ambient light sensor whose operational state is controlled through registers accessible through the I<sup>2</sup>C interface. The host can command the Si1132 to initiate on-demand UV index sensing or ambient light sensing. The host can also place the Si1132 in an autonomous operational state where it performs measurements at set intervals and interrupts the host after each measurement is completed. This results in an overall system power saving allowing the host controller to operate longer in its sleep state instead of polling the Si1132. For more details, refer to "AN498: Si114x Designer's Guide".

## 2.2. Ambient Light

The Si1132 has photodiodes capable of measuring both visible and infrared light. However, the visible photodiode is also influenced by infrared light. The measurement of illuminance requires the same spectral response as the human eye. If an accurate lux measurement is desired, the extra IR response of the visible-light photodiode must be compensated. Therefore, to allow the host to make corrections to the infrared light's influence, the Si1132 reports the infrared light measurement on a separate channel. The separate visible and IR photodiodes lend themselves to a variety of algorithmic solutions. The host can then take these two measurements and run an algorithm to derive an equivalent lux level as perceived by a human eye. Having the IR correction algorithm running in the host allows for the most flexibility in adjusting for system-dependent variables. For example, if the glass used in the system blocks visible light more than infrared light, the IR correction needs to be adjusted.

If the host is not making any infrared corrections, the infrared measurement can be turned off in the CHLIST parameter.

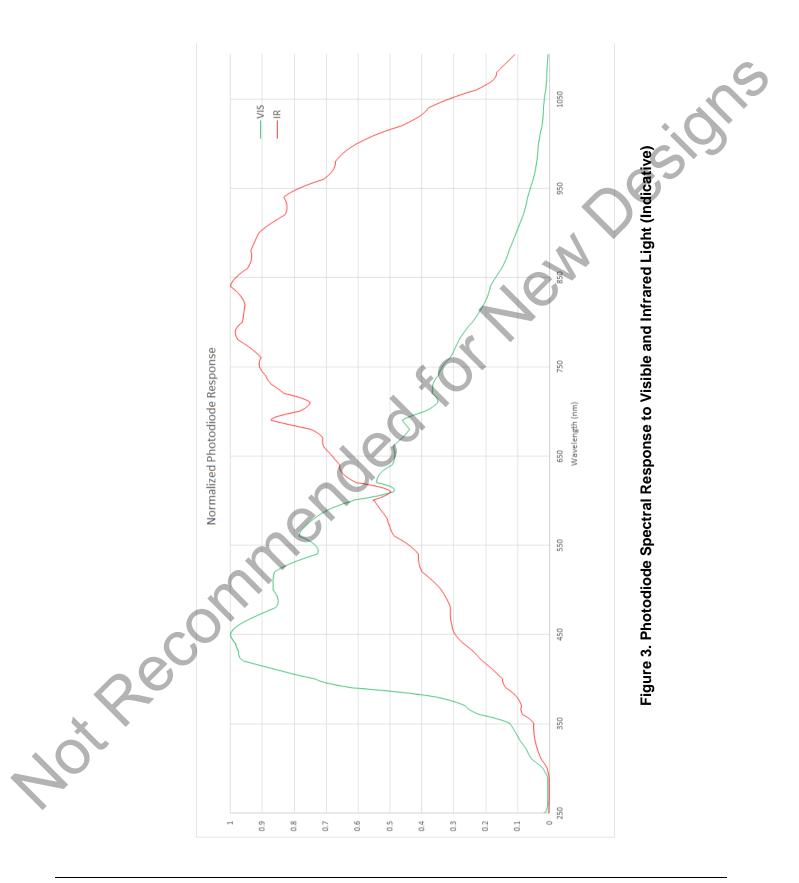
By default, the measurement parameters are optimized for indoor ambient light levels where it is possible to detect light levels as low as 6 lx. For operation under direct sunlight, the ADC can be programmed to operate in a high signal operation so that it is possible to measure direct sunlight without overflowing the 16-bit result.

For low-light applications, it is possible to increase the ADC integration time. Normally, the integration time is 25.6  $\mu$ s. By increasing this integration time to 410  $\mu$ s, the ADC can detect light levels as low as 1 lx. The ADC can be programmed with an integration time as high as 3.28 ms, allowing measurement to 100 mlx light levels. The ADC integration time for the Visible Light Ambient measurement can be programmed independently of the ADC integration time of the Infrared Light Ambient measurement. The independent ADC parameters allow operation under glass covers having a higher transmittance to Infrared Light than Visible Light.

When operating in the lower signal range, or when the integration time is increased, it is possible to saturate the ADC when the ambient light suddenly increases. Any overflow condition is reported in the RESPONSE register, and the corresponding data registers report a value of 0xFFFF. Based on either of these two overflow indicators, the host can adjust the ADC sensitivity. However, the overflow condition is not sticky. If the light levels return to a range within the capabilities of the ADC, the corresponding data registers begin to operate normally. The RESPONSE register will continue to hold the overflow condition until a NOP command is received. Even if the RESPONSE register has an overflow condition, commands are still accepted and processed.

The Si1132 can initiate ALS measurements either when explicitly commanded by the host or periodically through an autonomous process. Refer to "3. Operational Modes" on page 15 for additional details of the Si1132's Operational Modes.







## 2.3. Ultraviolet (UV) Index

The UV Index is a number linearly related to the intensity of sunlight reaching the earth and is weighted according to the CIE Erythemal Action Spectrum as shown in Figure 4. This weighting is a standardized measure of human skin's response to different wavelengths of sunlight from UVB to UVA. The UV Index has been standardized by the World Health Organization and includes a simplified consumer UV exposure level as shown in Figures 5 and 6.

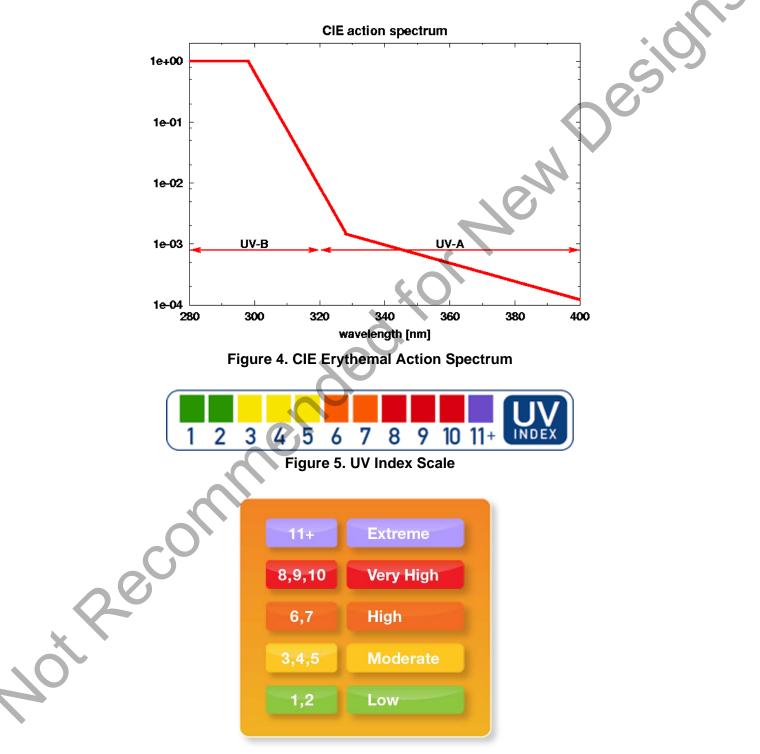


Figure 6. UV Levels



To enable UV reading, set the EN\_UV bit in CHLIST, and configure UCOEF [0:3] to the default values of 0x7B, 0x6B, 0x01, and 0x00. Also set the VIS\_RANGE and IR\_RANGE bits. If the sensor will be under an overlay that is not 100% transmissive to sunlight, contact Silicon Labs for more information on adjusting these coefficients.

Typically, after 285 µs, AUX\_DATA will contain a 16-bit value representing 100 times the sunlight UV Index. Host software must divide the results from AUX\_DATA by 100.

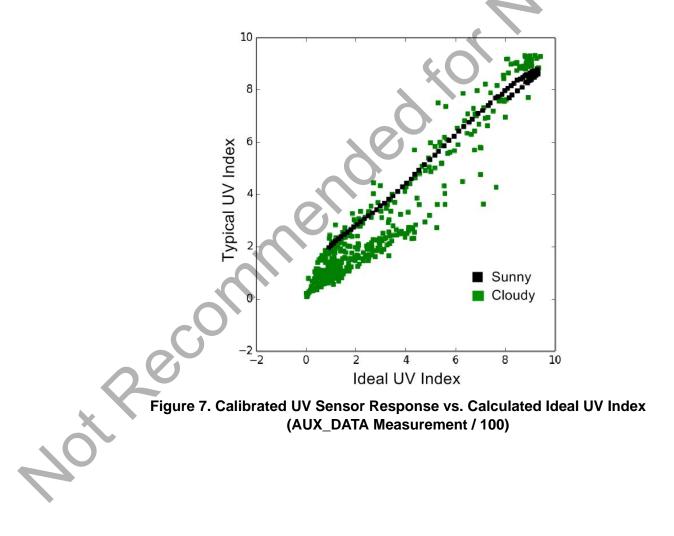
The accuracy of UV readings can be improved by using calibration parameters that are programmed into the Si1132 at Silicon Labs' production facilities to adjust for normal part-to-part variation. The calibration parameters are recovered from the Si1132 by writing Command Register @ address 0x18 with the value 0x12.

When the calibration parameters are recovered, they show up at I<sup>2</sup>C registers 0x22 to 0x2D. These are the same registers used to report the VIS, IR, and AUX measurements.

The use of calibration parameters is documented in the file, Si114x\_functions.h, which is part of the Si114x Programmer's Toolkit example source code and is downloadable from Silabs.com. The host code is expected to allocate memory for the Si114x\_CAL\_S structure. The Si114x\_calibration routine will then fill it up with the appropriate values.

Once the calibration parameters have been recovered the routine Si114x\_set\_ucoef is used to modify the default values that go into the UCOEF0 to UCOEF3 UV configuration registers to remove normal part-to-part variation.

The typical calibrated UV sensor response vs. calculated ideal UV Index is shown in Figure 7 for a large database of sunlight spectra from cloudy to sunny days and at various angles of the sun/time of day.





## 2.4. Host Interface

The host interface to the Si1132 consists of three pins:

- SCL
- SDA
- INT

SCL and SDA are standard open-drain pins as required for I<sup>2</sup>C operation.

The Si1132 asserts the INT pin to interrupt the host processor. The INT pin is an open-drain output. A pull-up resistor is needed for proper operation. As an open-drain output, it can be shared with other open-drain interrupt sources in the system.

For proper operation, the Si1132 is expected to fully complete its Initialization Mode prior to any activity on the I<sup>2</sup>C.

The INT, SCL, and SDA pins are designed so that it is possible for the Si1132 to enter the Off Mode by software command without interfering with normal operation of other I<sup>2</sup>C devices on the bus.

The Si1132 I<sup>2</sup>C slave address is 0x60. The Si1132 also responds to the global address (0x00) and the global reset command (0x06). Only 7-bit I<sup>2</sup>C addressing is supported; 10-bit I<sup>2</sup>C addressing is not supported. Conceptually, the I<sup>2</sup>C interface allows access to the Si1132 internal registers. Table 11 on page 24 is a summary of these registers.

An  $I^2C$  write access always begins with a start (or restart) condition. The first byte after the start condition is the  $I^2C$  address and a read-write bit. The second byte specifies the starting address of the Si1132 internal register. Subsequent bytes are written to the Si1132 internal register sequentially until a stop condition is encountered. An  $I^2C$  write access with only two bytes is typically used to set up the Si1132 internal address in preparation for an  $I^2C$  read.

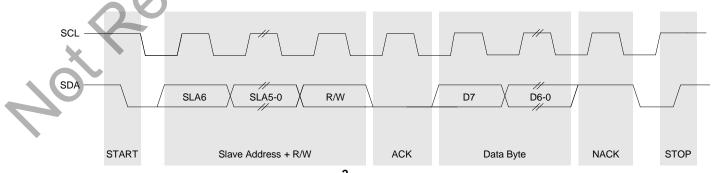
The I<sup>2</sup>C read access, like the I<sup>2</sup>C write access, begins with a start or restart condition. In an I<sup>2</sup>C read, the I<sup>2</sup>C master then continues to clock SCK to allow the Si1132 to drive the I<sup>2</sup>C with the internal register contents.

The Si1132 also supports burst reads and burst writes. The burst read is useful in collecting contiguous, sequential registers. The Si1132 register map was designed to optimize for burst reads for interrupt handlers, and the burst writes are designed to facilitate rapid programming of commonly used fields.

The internal register address is a six-bit (bit 5 to bit 0) plus an Autoincrement Disable (on bit 6). The Autoincrement Disable is turned off by default. Disabling the autoincrementing feature allows the host to poll any single internal register repeatedly without having to keep updating the Si1132 internal address every time the register is read.

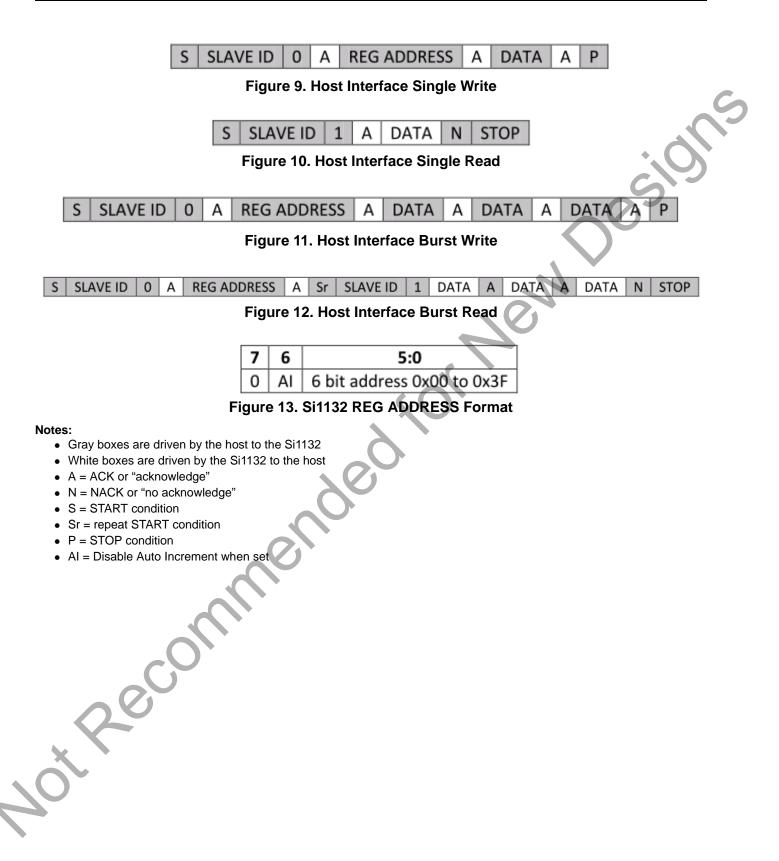
It is recommended that the host should read measurements (in the I<sup>2</sup>C Register Map) when the Si1132 asserts INT. Although the host can read any of the Si1132's I<sup>2</sup>C registers at any time, care must be taken when reading 2-byte measurements outside the context of an interrupt handler. The host could be reading part of the 2-byte measurement when the internal sequencer is updating that same measurement coincidentally. When this happens, the host could be reading a hybrid 2-byte quantity whose high byte and low byte are parts of different samples. If the host must read these 2-byte registers outside the context of an interrupt handler, the host should "double-check" a measurement if the measurement deviates significantly from a previous reading.

**I<sup>2</sup>C Broadcast Reset:** The I<sup>2</sup>C Broadcast Reset should be sent prior to any I<sup>2</sup>C register access to the Si1132. If any I<sup>2</sup>C register or parameter has already been written to the Si1132 when the I<sup>2</sup>C Broadcast Reset is issued, the host must send a reset command and reinitialize the Si1132 completely.











# 3. Operational Modes

The Si1132 can be in one of many operational modes at any one time. It is important to consider the operational mode since the mode has an impact on the overall power consumption of the Si1132. The various modes are:

- Off Mode
- Initialization Mode
- Standby Mode
- Forced Conversion Mode
- Autonomous Mode

### 3.1. Off Mode

ne V<sub>DD</sub> voltage is below

The Si1132 is in the Off Mode when  $V_{DD}$  is either not connected to a power supply or if the  $V_{DD}$  voltage is below the stated VDD\_OFF voltage described in the electrical specifications. As long as the parameters stated in Table 4, "Absolute Maximum Limits," on page 7 are not violated, no current will flow through the Si1132. In the Off Mode, the Si1132 SCL and SDA pins do not interfere with other I<sup>2</sup>C devices on the bus. Keeping V<sub>DD</sub> less than VDD\_OFF is not intended as a method of achieving lowest system current draw. The reason is that the ESD protection devices on the SCL, SDA and INT pins also from a current path through V<sub>DD</sub>. If V<sub>DD</sub> is grounded for example, then, current flow from system power to system ground through the SCL, SDA and INT pull-up resistors and the ESD protection devices.

Allowing V<sub>DD</sub> to be less than VDD\_OFF is intended to serve as a hardware method of resetting the Si1132 without a dedicated reset pin.

The Si1132 can also reenter the Off Mode upon receipt of either a general I<sup>2</sup>C reset or if a software reset sequence is initiated. When one of these software methods is used to enter the Off Mode, the Si1132 typically proceeds directly from the Off Mode to the Initialization Mode.

#### 3.2. Initialization Mode

When power is applied to  $V_{DD}$  and is greater than the minimum  $V_{DD}$  Supply Voltage stated in Table 1, "Recommended Operating Conditions," on page 4, the Si1132 enters its Initialization Mode. In the Initialization Mode, the Si1132 performs its initial startup sequence. Since the I<sup>2</sup>C may not yet be active, it is recommended that no I<sup>2</sup>C activity occur during this brief Initialization Mode period. The "Start-up time" specification in Table 1 is the minimum recommended time the host needs to wait before sending any I<sup>2</sup>C accesses following a power-up sequence. After Initialization Mode has completed, the Si1132 enters Standby Mode. The host must write 0x17 to the HW\_KEY register for proper operation.

#### 3.3. Standby Mode

The Si1132 spends most of its time in Standby Mode. After the Si1132 completes the Initialization Mode sequence, it enters Standby mode. While in Standby Mode, the Si1132 does not perform any measurements. However, the I<sup>2</sup>C interface is active and ready to accept reads and writes to the Si1132 registers. The internal Digital Sequence Controller is in its sleep state and does not draw much power. In addition, the INT output retains its state until it is cleared by the host.

I<sup>2</sup>C accesses do not necessarily cause the Si1132 to exit the Standby Mode. For example, reading Si1132 registers is accomplished without needing the Digital Sequence Controller to wake from its sleep state.

#### 3.4. Forced Conversion Mode

The Si1132 can operate in Forced Conversion Mode under the specific command of the host processor. The Forced Conversion Mode is entered if the ALS\_FORCE command is sent. Upon completion of the conversion, the Si1132 can generate an interrupt to the host if the corresponding interrupt is enabled.



## 3.5. Autonomous Operation Mode

The Si1132 can be placed in the Autonomous Operation Mode where measurements are performed automatically without requiring an explicit host command for every measurement. The ALS\_AUTO command is used to place the Si1132 in the Autonomous Operation Mode.

The Si1132 updates the  $I^2C$  registers for ALS automatically. Each measurement is allocated a 16-bit register in the  $I^2C$  map. It is possible to operate the Si1132 without interrupts. When doing so, the host poll rate must be at least twice the frequency of the conversion rates for the host to always receive a new measurement. The host can also choose to be notified when these new measurements are available by enabling interrupts.

The conversion frequencies for the ALS measurements are set up by the host prior to the ALS\_AUTO command. Recommended for New



# 4. Programming Guide

### 4.1. Command and Response Structure

All Si1132 I<sup>2</sup>C registers (except writes to the COMMAND register) are read or written without waking up the internal sequencer. A complete list of the I<sup>2</sup>C registers can be found in "4.5. I2C Registers" on page 24. In addition to the I<sup>2</sup>C Registers, RAM parameters are memory locations maintained by the internal sequencer. These RAM Parameters are accessible through a Command Protocol (see "4.6. Parameter RAM" on page 35). A complete list of the RAM Parameters can be found in "4.6. Parameter RAM" on page 35.

The Si1132 can operate either in Forced Measurement or Autonomous Mode. When in Forced Measurement mode, the Si1132 does not make any measurements unless the host specifically requests the Si1132 to do so via specific commands (refer to the Section 3.2). The CHLIST parameter needs to be written so that the Si1132 would know which measurements to make. The parameter MEAS\_RATE, when zero, places the internal sequencer in Forced Measurement mode. When in Forced Measurement mode, the internal sequencer wakes up only when the host writes to the COMMAND register. The power consumption is lowest in Forced Measurement mode (MEAS\_RATE = 0).

The Si1132 operates in Autonomous Operation mode when MEAS\_RATE is non-zero. The MEAS\_RATE represents the time interval at which the Si1132 wakes up periodically. Up to three measurements are made (ALS\_VIS, ALS\_IR and AUX) depending on which measurements are enabled via the upper bits of the CHLIST Parameter. All three measurements are made in the following sequence: ALS\_VIS, ALS\_IR and AUX.

The ALS Measurement group consists of the Visible Light Ambient Measurement (ALS\_VIS), the Infrared Light Ambient Measurement (ALS\_IR) and the Auxiliary measurement (AUX). Each measurement group has three measurements each. The Channel List (CHLIST) parameter enables the specific measurements for that measurement grouping.

Each measurement (ALS\_VIS, ALS\_IR, AUX) are controlled through a combination of I2C Register or Parameter RAM. Tables 7 to 9 below summarize the properties and resources used for each measurement.



## 4.2. Command Protocol

The I<sup>2</sup>C map implements a bidirectional message box between the host and the Si1132 Sequencer. Host-writable I<sup>2</sup>C registers facilitate host-to-Si1132 communication, while read-only I<sup>2</sup>C registers are used for Si1132-to-host communication.

Unlike the other host-writable I<sup>2</sup>C registers, the COMMAND register causes the internal sequencer to wake up from Standby mode to process the host request.

When a command is executed, the RESPONSE register is updated. Typically, when there is no error, the upper four bits are zeros. To allow command tracking, the lower four bits implement a 4-bit circular counter. In general, if the upper nibble of the RESPONSE register is non-zero, this indicates an error or the need for special processing.

The PARAM\_WR and PARAM\_RD registers are additional mailbox registers.

In addition to the registers in the I<sup>2</sup>C map, there are environmental parameters accessible through the Command/ Response interface. These parameters are stored in the internal ram space. These parameters generally take more I<sup>2</sup>C accesses to read and write. The Parameter RAM is described in "4.6. Parameter RAM" on page 35.

For every write to the Command register, the following sequence is required:

- 1. Write 0x00 to Command register to clear the Response register.
- 2. Read Response register and verify contents are 0x00.
- 3. Write Command value from Table 5 into Command register.
- 4. Read the Response register and verify contents are now non-zero. If contents are still 0x00, repeat this step.

The Response register will be incremented upon the successful completion of a Command. If the Response register remains 0x00 for over 25 ms after the Command write, the entire Command process should be repeated from Step 1.

Step 4 above is not applicable to the Reset Command because the device will reset itself and does not increment the Response register after reset. No Commands should be issued to the device for at least 1 ms after a Reset is issued.

COMMAND R	egister	PARAM_W	PARAM_RD	Error Code in	Description
Name	Encoding	R Register	Register	RESPONSE Register	Description
PARAM_QUERY	100 aaaaa		nnnn nnnn	$\checkmark$	Reads the parameter pointed to by bitfield [4:0] and writes value to PARAM_RD. See Table 12 for parameters.
PARAM_SET	101 aaaaa	dddd dddd	nnnn nnnn	$\checkmark$	Sets parameter pointed by bitfield [4:0] with value in PARAM_WR, and writes value out to PARAM_RD. See Table 12 for parameters.
NOP	000 00000	—	—	√	Forces a zero into the RESPONSE register
RESET	000 00001	—	—	√	Performs a software reset of the firmware
BUSADDR	000 00010	—	_	—	Modifies I <sup>2</sup> C address
Reserved	000 00011	_	_	—	—
Reserved	000 00100		_	_	
Reserved	000 00101	—	_	—	_

## Table 5. Command Register Summary



COMMAND F	Register	PARAM_W	PARAM_RD	Error Code in	Description
Name	Encoding	R Register	Register	RESPONSE Register	Description
GET_CAL	0001 0010	—	—		Reports calibration data to I <sup>2</sup> C registers 0x22–0x2D
ALS_FORCE	000 00110		_	$\checkmark$	Forces a single ALS measurement
Reserved	000 00111	—			- (9)
Reserved	000 01000		_	—	-0.2
Reserved	000 01001	—	_	_	
ALS_PAUSE	000 01010	—	_	✓	Pauses autonomous ALS
Reserved	000 01011	_	—	—	_
Reserved	000 01100	_		✓	-
Reserved	000 01101	_	—		- 0
ALS_AUTO	000 01110	—	—	1	Starts/Restarts an autonomous ALS Loop
Reserved	000 01111	_	_		—
Reserved	000 1xxxx	—	_	κÐ.	—

## Table 5. Command Register Summary (Continued)

## Table 6. Response Register Error Codes

RESPONSE Register	Description
	NO_ERROR. The lower bit is a circular counter and is incremented every time a command has completed. This allows the host to keep track of commands sent to the Si1132. The circular counter may be cleared using the NOP command.
	INVALID_SETTING. An invalid setting was encountered. Clear using the NOP command.
	ALS_VIS_ADC_OVERFLOW. Indicates visible ambient light channel conversion overflow.
	ALS_IR_ADC_OVERFLOW. Indicates infrared ambient light channel conversion overflow.
1000 1110	AUX_ADC_OVERFLOW. Indicates auxiliary channel conversion overflow.
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## 4.3. Resource Summary

	Channel Enable	Interrupt Status Output	Interrupt Enable
ALS Visible	EN_ALS_VIS in CHLIST[4]	ALS_INT[1:0] in IRQ_ STATUS[1:0]	ALS_IE[1:0] in IRQ_ENABLE[1:0]
ALS IR	EN_ALS_IR in CHLIST[5]		000
Auxiliary Measurement	EN_AUX in CHLIST[6]		<u> </u>
	nnenor		

#### Table 7. Resource Summary for Interrupts





Measurement Channel	ADC Output	ADC Input Source	ADC Recovery Count	ADC High Signal Mode	ADC Clock Divider	ADC Alignm
ALS Visible	ALS_VIS_DATA1 / ALS_VIS_DATA0		VIS_ADC_REC in ALS_VIS_ADC_COUNTER [6:4]	VIS_RANGE in ALS_VIS_ADC_MISC[5]	ALS_VIS_ ADC_GAIN [3:0]	ALS_V ALIG in ALS ENCODII
ALS IR	ALS_IR_DATA1[7:0] / ALS_IR_DATA0[7:0]		IR_ADC_REC in ALS_IR_ADC_COUNTER [6:4]	IR_RANGE in ALS_IR_ADC_MISC[5]	ALS_IR_ ADC_GAIN [3:0]	ALS_I ALIG in ALS ENCODII
Auxiliary Measurement	AUX_DATA1[7:0] / AUX_DATA0[7:0]	AUX_ADCMUX[7:0]		_	_	_
			ended			
	, Re	conin	erdeo			



Pin Name	Output Drive Disable	Analog Voltage Input Enable		
INT	INT_OE in INT_CFG[0]	ANA_IN_KEY[31:0]		

The interrupts of the Si1132 are controlled through the INT\_CFG, IRQ\_ENABLE, IRQ\_MODE1, IRQ\_MODE2 and IRQ\_STATUS registers.

The INT hardware pin is enabled through the INT\_OE bit in the INT\_CFG register. The hardware essentially performs an AND function between the IRQ\_ENABLE register and IRQ\_STATUS register. After this AND function, if any bits are set, the INT pin is asserted. The host is responsible for clearing the interrupt by writing to the IRQ\_STATUS register. When the specific bits of the IRQ\_STATUS register is written with 1, that specific IRQ\_STATUS bit is cleared.

Typically, the host software is expected to read the IRQ\_STATUS register, stores a local copy, and then writes the same value back to the IRQ\_STATUS to clear the interrupt source. The INT\_CFG register is normally written with 1.

The IRQ\_MODE1, IRQ\_MODE2 and IRQ\_ENABLE registers work together to define how the internal sequencer sets bits in the IRQ\_STATUS register (and as a consequence, asserting the INT pin).

The ALS interrupts are described in Table 10.

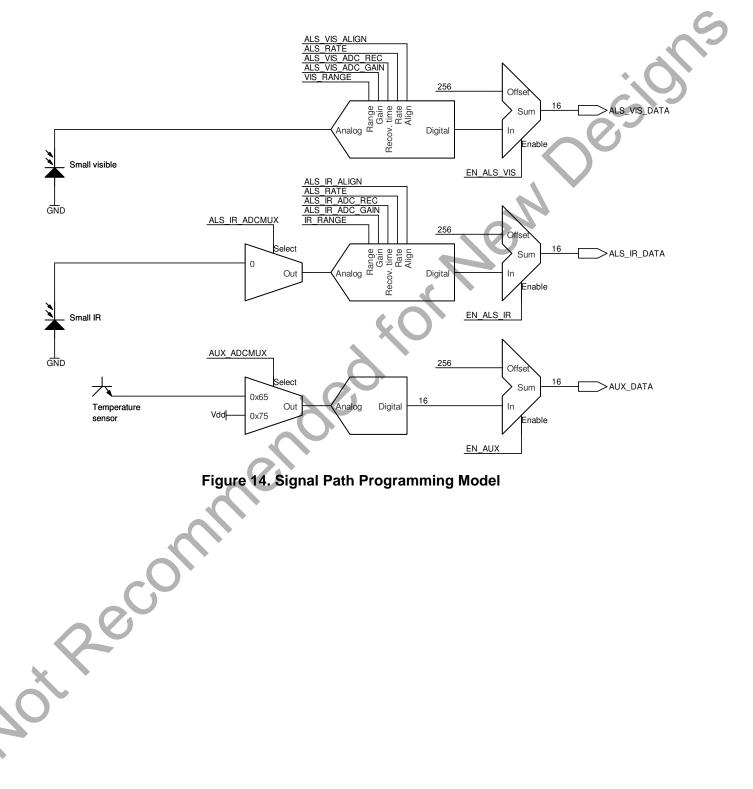
### Table 10. Ambient Light Sensing Interrupt Resources

	IRQ_ENABLE[1:0] ALS_IE[1:0]		Description	
			Description	
	0	0	No ALS Interrupts	
	0	1	ALS_INT set after every ALS_VIS or UV sample	
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## 4.4. Signal Path Software Model

The following diagram gives an overview of the signal paths, along with the I<sup>2</sup>C register and RAM Parameter bit fields that control them. Sections with detailed descriptions of the I<sup>2</sup>C registers and Parameter RAM follow.





# 4.5. I<sup>2</sup>C Registers

I <sup>2</sup> C Register Name	Address	7	6	5	4	3	2	1	0
PART_ID	0x00			1	PART	_ID		•	
REV_ID	0x01				REV_	ID		G	
SEQ_ID	0x02				SEQ_	ID		0,	
INT_CFG	0x03							)	INT_OE
IRQ_ENABLE	0x04								ALS_IE
HW_KEY	0x07				HW_K	EΥ	7		
MEAS_RATE0	0x08				MEAS_R	ATE0	5		
MEAS_RATE1	0x09				MEAS_R	ATE1			
Reserved	0x0A				~				
Reserved	0x0B			(	kO.	>			
Reserved	0x0C								
Reserved	0x0D			0					
Reserved	0x0E		2	0					
Reserved	0x0F		~	5					
Reserved	0x10	C							
Reserved	0x11								
Reserved	0x12								
UCOEF0	0x13	$\overline{\mathbf{O}}$			UCOE	F0			
UCOEF1	0x14	)			UCOE	F1			
UCOEF2	0x15		UCOEF2						
UCOEF3	0x16				UCOE	F3			
PARAM_WR	0x17				PARAM	_WR			
COMMAND	0x18				COMM	AND			
RESPONSE	0x20				RESPO	NSE			
IRQ_STATUS	0x21			CMD_INT				ALS_	INT
ALS_VIS_ DATA0	0x22				ALS_VIS_	DATA0			





I <sup>2</sup> C Register Name	Address	7	6	5	4	3	2	1	0
ALS_VIS_ DATA1	0x23		ALS_VIS_DATA1						
ALS_IR_DATA0	0x24				ALS_IR_E	DATA0		+	O'
ALS_IR_DATA1	0x25				ALS_IR_E	DATA1		S	
Reserved	0x26							0	
Reserved	0x27								
Reserved	0x28						~		
Reserved	0x29						~~~		
Reserved	0x2A						0		
Reserved	0x2B								
AUX_DATA0/ UVINDEX0	0x2C		AUX_DATA0/UVINDEX0						
AUX_DATA1/ UVINDEX1	0x2D		AUX_DATA1/UVINDEX1						
PARAM_RD	0x2E		PARAM_RD						
CHIP_STAT	0x30		(				RUNNING	SUSPEND	SLEEF
ANA_IN_KEY	0x3B– 0x3E	(	$\sim$		ANA_IN_	_KEY			
o't P	ecc	SUUL							

Table 11. I<sup>2</sup>C Register Summary (Continued)



PART\_ID @ 0x00

Bit	7	6	5	4	3	2	1	0
Name				PAR	T_ID			
Туре					२			29
Reset value = 001	1 0010						~?	5
REV_ID @ 0x1							$\mathbf{\nabla}$	
Bit	7	6	5	4	3	2	1	0
Name				RE	/_ID	6		
Туре					R			
Reset value = 000	0 0000				~``			
SEQ_ID @ 0x02								
Bit	7	6	5	4	3	2	1	0
Name		1	0	SEC	DI_Q	1		-
Туре		0			२			
Reset value = 000	0 1000		0					
Bit	Name				Function			
7:0 5	SEQ_ID	0x08	<b>er Revisio</b> Si11	<b>n.</b> 32-A10 (MA	JOR_SEQ=	1, MINOR_	SEQ=0)	
o Re	ç							



## INT\_CFG @ 0x03

Bit	7	6	5	4	3	2	1	0	S
Name								INT_OE	
Туре							RW	RW	

Reset value	e = 0000 0000	
Bit	Name	Function
7:2	Reserved	Reserved.
0	INT_OE	INT Output Enable. INT_OE controls the INT pin drive 0: INT pin is never driven 1: INT pin driven low whenever an IRQ_STATUS and its corresponding IRQ_ENABLE bits match

## IRQ\_ENABLE @ 0x04

Bit 7 6	5 4	3	2	1	0
Name					ALS_IE
Туре				R	N

Reset value = 0000 0000

Bit	Name	Function
7:1	Reserved	Reserved.
0	ALS_IE	ALS Interrupt Enable.
		Enables interrupts when VIS bit or UV bit in CHLIST is enabled.
		0: INT never asserts due to VIS or UV activity
		1: Assert INT pin whenever VIS or UV measurements are ready



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HW\_KEY @ 0x07

Bit	7	6	5	4	3	2	1	0	
Name	e		HW_KEY						
Туре	)			R	W				
et valu	ue = 0000 000	)					2	)	
Bit	Name				Function				
7:0	HW_KEY	_KEY The system must write the value 0x17 to this register for proper Si1132 operation.							
	ATE0: MEAS_						r si risz oper		
	ATE0: MEAS_				3	2	1	0	
AS_R/	ATE0: MEAS_	RATE Data Wo	ord Low Byte	e @ 0x08	3 RATE[7:0]	6			
AS_R/ Bit	ATEO: MEAS_ 7	RATE Data Wo	ord Low Byte	e @ 0x08 4 MEAS_	3	6			
AS_R/ Bit Nam Type	ATEO: MEAS_ 7	RATE Data Wo	ord Low Byte	e @ 0x08 4 MEAS_	<b>3</b> RATE[7:0]	6			
AS_R/ Bit Nam Type	ATEO: MEAS_ 7 ne e	RATE Data Wo	ord Low Byte	e @ 0x08 4 MEAS_	<b>3</b> RATE[7:0]	2			

measurements specified in CHLIST are made. Note that for the Si1132 with SEQ\_ID=0x01, there is a code error that places MEAS\_RATE0 at 0x0A with MEAS\_RATE1 at 0x08 instead. This will be fixed in future revisions of the Si1132.



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#### MEAS\_RATE1: MEAS\_RATE Data Word High Byte @ 0x09

Bit	7	6	5	4	3	2	1	0	S
Name	·			MEAS_R	ATE[15:8]				
Туре				R	W			39	

Reset value	= 0000 0000	
Bit	Name	Function
7:0	MEAS_RATE[15:8]	MEAS_RATE1 and MEAS_RATE0 together form a 16-bit value: MEAS_RATE[15:0]. The 16-bit value, when multiplied by 31.25 µs, represents the time duration between wake-up periods where measurements are made. Once the device wakes up, all measurements specified in CHLIST are made. Note that for the Si1132 with SEQ_ID=0x01, there is a code error that places MEAS_RATE0 at 0x0A and MEAS_RATE1 at 0x08 instead. This will be fixed in future revisions of the Si1132.

#### PARAM\_WR @ 0x17

Bit	7	6	5	4	3	2	1	0		
Name		PARAM_WR								
Туре		RW								

Reset value = 0000 0000

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Bit	Name	Function
7:0	PARAM_WR	Mailbox register for passing parameters from the host to the sequencer.

O



#### COMMAND @ 0x18

Bit	7	6	5	4	3	2	1	0
Name			L	COMM	IAND		1	
Туре				RV	V			· O
eset value =	= 0000 0000							6

Bit	Name	Function
7:0	COMMAND	COMMAND Register.
		The COMMAND Register is the primary mailbox register into the internal sequencer. Writing to the COMMAND register is the only I <sup>2</sup> C operation that wakes the device from standby mode.

#### RESPONSE @ 0x20

Bit	7	6	5	4 3	2	1	0	
Name				RESPONSE				
Туре		RW						

Bit	Name	Function
7:0	RESPONSE	The Response register is used in conjunction with command processing. When an e is encountered, the response register will be loaded with an error code. All error code will have the MSB is set.
	2000	The error code is retained until a RESET or NOP command is received by the sequencer. Other commands other than RESET or NOP will be ignored. However, a autonomous operation in progress continues normal operation despite any error. 0x00–0x0F: No Error. Bits 3:0 form an incrementing roll-over counter. The roll over counter in bit 3:0 increments when a command has been executed by the Si1132. C autonomous measurements have started, the execution timing of any command becomes non-deterministic since a measurement could be in progress when the COMMAND register is written. The host software must make use of the rollover cou to ensure that commands are processed. 0x80: Invalid Command Encountered during ALS-VIS measurement 0x8D: ADC Overflow encountered during ALS-IR measurement 0x8E: ADC Overflow encountered during AUX measurement



#### IRQ\_STATUS @ 0x21

									_
Bit	7	6	5	4	3	2	1	0	G
Name			CMD_INT					ALS_INT	
Туре		·	RW				R	W	

Reset value = 0000 0000

Bit	Name	Function
7:6	Reserved	Reserved.
5	CMD_INT	Command Interrupt Status.
4:2	Reserved	Reserved.
1:0	ALS_INT	ALS Interrupt Status. (Refer to Table 13 for encoding.)
Note: If t	he correspondin	g IRQ_ENABLE bit is also set when the IRQ_STATUS bit is set, the INT pin is asserted.

### ALS\_VIS\_DATA0: ALS\_VIS\_DATA Data Word Low Byte @ 0x22

Bit	7 6 5 4 3 2 1 0									
Name		ALS_VIS_DATA[7:0]								
Туре				R	W					

	Bit	Name	Function
	7:0	ALS_VIS_DATA[7:0]	ALS VIS Data LSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to "AN498: Si114x Designer's Guide", section "5.6.2 Host Interrupt Latency".
2	ot	2ecol.	



## ALS\_VIS\_DATA1: ALS\_VIS\_DATA Data Word High Byte @ 0x23

Bit	7	6	5	4	3	2	1	0			
Name		ALS_VIS_DATA[15:8]									
Туре		RW + C									
Reset value = 0000	0000							S			

Bit	Name	Function
7:0		<b>ALS VIS Data MSB.</b> Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to "AN498: Si114x Designer's Guide", section "5.6.2 Host Interrupt Latency".

### ALS\_IR\_DATA0: ALS\_IR\_DATA Data Word Low Byte@ 0x24

Bit	7	6	5	4	3	2	1	0
Name				ALS_IR_	DATA[7:0]			
Туре				R	W			

Reset value = 0000 0000

Bit	Name	Function
7:0		ALS IR Data LSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to "AN498: Si114x Designer's Guide", section "5.6.2 Host Interrupt Latency".

## ALS\_IR\_DATA1: ALS\_IR\_DATA Data Word High Byte @ 0x25

Bit	7 6 5 4 3 2 1 0								
Name	0		ALS_IR_C	ATA[15:8]					
Туре	S		R	W					

	Bit	Name	Function
2	7:0		ALS IR Data MSB. Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to "AN498: Si114x Designer's Guide", section "5.6.2 Host Interrupt Latency".



## AUX\_DATA0/UVINDEX0: AUX\_DATA Data Word Low Byte @ 0x2C

Bit	7	7 6 5 4 3 2 1 0										
Name		AUX_DATA[7:0]										
Туре		RW										
Reset value	= 0000 0000	1						C				

Bit	Name	Function
7:0		AUX Data LSB. Once autonomous measurements have started, this register must be
		read after INT has asserted but before the next measurement is made. Refer to
		"AN498: Si114x Designer's Guide", section "5.6.2 Host Interrupt Latency".

## AUX\_DATA1/UVINDEX1: AUX\_DATA Data Word High Byte @ 0x2D

Bit	7	6	5	4	3	2	1	0	
Name				AUX_DA	TA[15:8]				
Туре				R	W				

Reset value = 0000 0000

Bit	Name	Function
7:0	AUX_DATA[15:8]	<b>AUX Data MSB.</b> Once autonomous measurements have started, this register must be read after INT has asserted but before the next measurement is made. Refer to "AN498: Si114x Designer's Guide", section "5.6.2 Host Interrupt Latency".

PARAM_RD @ 0x2E										
Bit	7 6	5	4	3	2	1	0			
Name	-0	PARAM_RD								
Туре	0		R	W						

Bit	Name	Function
7:0	PARAM_RD	Mailbox register for passing parameters from the sequencer to the host.



#### CHIP\_STAT @ 0x30

		RUNNING	SUSPEND	SLEEP
·		R	R	+ R
			R	R R

Bit	Name	Function
7:3	Reserved	Reserved
2	RUNNING	Device is awake.
1	SUSPEND	Device is in a low-power state, waiting for a measurement to complete.
0	SLEEP	Device is in its lowest power state.

#### ANA\_IN\_KEY @ 0x3B to 0x3E

Bit	7	6	5	4	3	2	1	0
0x3B	ANA_IN_KEY[31:24]							
0x3C	ANA_IN_KEY[23:16]							
0x3D	ANA_IN_KEY[15:8]							
0x3E	ANA_IN_KEY[7:0]							
Туре	RW							

Reset value = 0000 0000

Bit	Name	Function
31:0	ANA_IN_KEY[31:0]	Reserved.
NOI	200	



## 4.6. Parameter RAM

Parameters are located in internal memory and are not directly addressable over I<sup>2</sup>C. They must be indirectly accessed using the PARAM\_QUERY and PARAM\_SET commands described in "4.2. Command Protocol" on page 18.

					•				
Parameter Name	Offset	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit (
I2C_ADDR	0x00		•		I <sup>2</sup> C Address				
CHLIST	0x01	EN_UV	EN_AUX	EN_ALS_IR	EN_ALS_VIS			5	
Reserved	0x02				1			75	
Reserved	0x03					<			
Reserved	0x04			Reserve	ed (always set t	o 0)	$\mathbf{\nabla}$		
Reserved	0x05					Reserv	ved (alwa	ays set	to 0)
ALS_ENCODING	0x06			ALS_IR_ ALIGN	ALS_VIS_ ALIGN	Reserv	ved (alwa	ays set	to 0)
Reserved	0x07								
Reserved	0x08								
Reserved	0x09								
Reserved	0x0A			X	9				
Reserved	0x0B			7					
Reserved	0x0C								
Reserved	0x0D		Reserved (do not modify from default setting of 0x02)						
ALS_IR_ADCMUX	0x0E		ALS_IR_ADCMUX						
AUX_ADCMUX	0x0F			AUX A	DC Input Select	ion			
ALS_VIS_ ADC_COUNTER	0x10		5	VIS_ADC_R	EC	Reserv	ved (alwa	ays set	to 0)
ALS_VIS_ADC_GAIN	0x11	$\sim$						LS_VIS DC_GA	
ALS_VIS_ADC_MISC	0x12		erved s set to 0)	VIS_RANGE	Rese	rved (alw	ays set	to 0)	
Reserved	0x13		Reser	ved (do not mo	dify from defau	It setting	of 0x40)		
Reserved	0x14– 0x15		Reser	ved (do not mo	dify from defau	It setting	of 0x00)		
Reserved	0x1B		Reser	ved (do not mo	dify from defau	It setting	of 0x00)		
Reserved	0x1C								
ALS_IR_ ADC_COUNTER	0x1D			IR_ADC_RE	C	Reserv	ved (alwa	ays set	to 0)
ALS_IR_ADC_GAIN	0x1E							ALS_IR DC_GA	
ALS_IR_ADC_MISC	0x1F		erved s set to 0)	IR_RANGE	Rese	rved (alw	ays set	to 0)	
				•	•				

#### Table 12. Parameter RAM Summary Table



I2C @ 0x00

Bit	7	6	5	4	3	2	1	0		
Name		I <sup>2</sup> C Address[7:0]								
Туре		RW								
eset value = 0	000 0000									

[	Bit	Name	Function
	7:0		Specifies a new I <sup>2</sup> C Address for the device to respond to. The new address takes effect when a BUSADDR command is received.

#### CHLIST @ 0x01

Bit	7	6	5	4	3 2	1	0
Name	EN_UV	EN_AUX	EN_ALS_IR	EN_ALS_VIS			
Type RW							
Reset value = 0000 0000							

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Bit	Name	Function
7	EN_UV	Enables UV Index, data stored in AUX_DATA1[7:0] and AUX_DATA0[7:0]
6	EN_AUX	Enables Auxiliary Channel, data stored in AUX_DATA1[7:0] and AUX_DATA0[7:0].
5	EN_ALS_IR	Enables ALS IR Channel, data stored in ALS_IR_DATA1[7:0] and ALS_IR_DATA0[7:0].
4	EN_ALS_VIS	Enables ALS Visible Channel, data stored in ALS_VIS_DATA1[7:0] and ALS_VIS_DA-TA0[7:0].
3:0	Reserved	
	r proper operation eration is requeste	, CHLIST must be written with a non-zero value before forced measurements or autonomous



 $\checkmark$ 

#### ALS\_ENCODING @ 0x06

Bit	7	6	5	4	3	2	1	0	6
Name			ALS_IR_ALIGN	ALS_VIS_ALIGN					
Туре			RW	RW			·	•.0	

Reset value = 0000 0000

Bit	Name	Function
7:6	Reserved	
5	ALS_IR_ALIGN	When set, the ADC reports the least significant 16 bits of the 17-bit ADC when performing ALS VIS Measurement. Reports the 16 MSBs when cleared.
4	ALS_VIS_ALIGN	When set, the ADC reports the least significant 16 bits of the 17-bit ADC when performing ALS IR Measurement. Reports the 16 MSBs when cleared.
3:0	Reserved	Always set to 0.

#### ALS\_IR\_ADCMUX @ 0x0E

				*				
Bit	7	6	5	4	3	2	1	0
Name				ALS_IR_	ADCMUX			
Туре			2	R	W			

	Bit	Name	Function
	7:0		Selects ADC Input for ALS_IR Measurement.
			0x00: Small IR photodiode
20		Recom	



## AUX\_ADCMUX @ 0x0F

Bit	7	6	5	4	3	2	1	0	6
Name				AUX_AD0	CMUX[7:0]				$\sim$
Туре				R	W			•.0	
Reset valu	ue = 0110 010	01						6	7

Bit	Name	Function
7:0	AUX_ADCMUX[7:0]	Selects input for AUX Measurement. These measurements are referenced to GND. 0x65: Temperature (Should be used only for relative temperature measurement. Absolute Temperature not guaranteed) 0x75: V <sub>DD</sub> voltage

### ALS\_VIS\_ADC\_COUNTER @ 0x10

Bit	7	6	5	4	3	2	1	0
Name		VIS	_ADC_REC[	2:0]				
Туре		RW	R/W	R/W				

Reset value = 0111 0000

Bit	Name	Function
7	Reserved	
6:4	VIS_ADC_REC[2:0]	Recovery period the ADC takes before making a ALS-VIS measurement. 000: 1 ADC Clock (50 ns times 2 <sup>ALS_VIS_ADC_GAIN</sup> ) 001: 7 ADC Clock (350 ns times 2 <sup>ALS_VIS_ADC_GAIN</sup> ) 010: 15 ADC Clock (750 ns times 2 <sup>ALS_VIS_ADC_GAIN</sup> ) 011: 31 ADC Clock (1.55 µs times 2 <sup>ALS_VIS_ADC_GAIN</sup> ) 100: 63 ADC Clock (3.15 µs times 2 <sup>ALS_VIS_ADC_GAIN</sup> ) 101: 127 ADC Clock (6.35 µs times 2 <sup>ALS_VIS_ADC_GAIN</sup> ) 101: 255 ADC Clock (12.75 µs times 2 <sup>ALS_VIS_ADC_GAIN</sup> ) 111: 511 ADC Clock (25.55 µs times 2 <sup>ALS_VIS_ADC_GAIN</sup> ) The recommended VIS_ADC_REC value is the one's complement of ALS_VIS_ADC_GAIN.
3:0	Reserved	Always set to 0.



## ALS\_VIS\_ADC\_GAIN @ 0x11

Bit	7	6	5	4	3	2	1	0
Name						ALS_V	/IS_ADC_GA	IN[2:0]
Туре						RW	R/W	RW
Reset valu	ue = 0000 00	00						6

Bit	Name	Function
7:3	Reserved	
2:0	ALS_VIS_ADC_GAIN[2:0]	Increases the ADC integration time for ALS Visible measurements by a factor of (2 ^ ALS_VIS_ADC_GAIN). This allows visible light measurement under dark glass. The maximum gain is 128 (0x7). For Example: 0x0: ADC Clock is divided by 1 0x4: ADC Clock is divided by 16 0x6: ADC Clock is divided by 64

## ALS\_VIS\_ADC\_MISC @ 0x12

Bit	7	6	5	4	3	2	1	0
Name			VIS_RANGE	0				
Туре			RW	<b>J</b>				

Bit	Name	Function
7:6	Reserved	
5	VIS_RANGE	<ul> <li>When performing ALS-VIS measurements, the ADC can be programmed to operate in high sensitivity operation or high signal range.</li> <li>The high signal range is useful in operation under direct sunlight.</li> <li>0: Normal Signal Range</li> <li>1: High Signal Range (Gain divided by 14.5)</li> </ul>
4:0	Reserved	



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#### ALS\_IR\_ADC\_COUNTER @ 0x1D

Bit	7	6	5	4	3	2	1	0	6
Name		IR_	_ADC_REC[2	2:0]					
Туре			RW		·			•.0	

Reset value = 0111 0000

7       Reserved         6:4       IR_ADC_REC[2:0]       Recovery period the ADC takes before making a ALS-IR mt 000: 1 ADC Clock (50 ns times 2^ALS_IR_ADC_GAIN) 01: 7 ADC Clock (350 ns times 2^ALS_IR_ADC_GAIN) 010: 15 ADC Clock (750 ns times 2^ALS_IR_ADC_GAIN) 111: 31 ADC Clock (1.55 µs times 2^ALS_IR_ADC_GAIN) 100: 63 ADC Clock (1.55 µs times 2^ALS_IR_ADC_GAIN) 101: 127 ADC Clock (2.55 µs times 2^ALS_IR_ADC_GAIN) 110: 125 ADC Clock (2.55 µs times 2^ALS_IR_ADC_GAIN) 111: 511 ADC Clock (2.55 µs times 2^ALS_IR_ADC_GAIN) The recommended IR_ADC_REC value is the one's ALS_IR_ADC_GAIN.         3:0       Reserved	Function	Name	Bit
000: 1 ADC Clock (50 ns times 2 <sup>ALS_IR_ADC_GAIN</sup> )         001: 7 ADC Clock (350 ns times 2 <sup>ALS_IR_ADC_GAIN</sup> )         010: 15 ADC Clock (750 ns times 2 <sup>ALS_IR_ADC_GAIN</sup> )         011: 31 ADC Clock (1.55 µs times 2 <sup>ALS_IR_ADC_GAIN</sup> )         100: 63 ADC Clock (3.15 µs times 2 <sup>ALS_IR_ADC_GAIN</sup> )         101: 127 ADC Clock (6.35 µs times 2 <sup>ALS_IR_ADC_GAIN</sup> )         101: 127 ADC Clock (6.35 µs times 2 <sup>ALS_IR_ADC_GAIN</sup> )         110: 255 ADC Clock (12.75 µs times 2 <sup>ALS_IR_ADC_GAIN</sup> )         111: 511 ADC Clock (25.55 µs times 2 <sup>ALS_IR_ADC_GAIN</sup> )         The recommended IR_ADC_REC value is the one's         ALS_IR_ADC_GAIN.         3:0       Reserved		Reserved	7
3:0 Reserved Always set to 0.	000: 1 ADC Clock (50 ns times $2^{ALS}IR_ADC_GAIN$ ) 001: 7 ADC Clock (350 ns times $2^{ALS}IR_ADC_GAIN$ ) 010: 15 ADC Clock (750 ns times $2^{ALS}IR_ADC_GAIN$ ) 011: 31 ADC Clock (1.55 µs times $2^{ALS}IR_ADC_GAIN$ ) 100: 63 ADC Clock (3.15 µs times $2^{ALS}IR_ADC_GAIN$ ) 101: 127 ADC Clock (6.35 µs times $2^{ALS}IR_ADC_GAIN$ ) 101: 255 ADC Clock (12.75 µs times $2^{ALS}IR_ADC_GAIN$ ) 110: 255 ADC Clock (25.55 µs times $2^{ALS}IR_ADC_GAIN$ ) 111: 511 ADC Clock (25.55 µs times $2^{ALS}IR_ADC_GAIN$ ) 110: 255 µs times $2^{ALS}IR_ADC_GAIN$ )		6:4
nende		Deserved	2.0
o'R'		con	
			o'.

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## ALS\_IR\_ADC\_GAIN @ 0x1E

Bit	7	6	5	4	3	2	1	0
Name						ALS_I	R_ADC_GA	IN[2:0]
Туре	R/W R/W R/						R/W	
Reset val	ue = 0000 00	00			6			

Bit	Name	Function
7:3	Reserved	
2:0	ALS_IR_ADC_GAIN[2:0]	Increases the ADC integration time for IR Ambient measurements by a fac- tor of (2 ^ ALS_IR_ADC_GAIN). The maximum gain is 128 (0x7). For Example: 0x0: ADC Clock is divided by 1 0x4: ADC Clock is divided by 16 0x6: ADC Clock is divided by 64

### ALS\_IR\_ADC\_MISC @ 0x1F

Bit	7	6	5	4	3	2	1	0
Name			IR_RANGE					
Туре			RW	$\sim$				

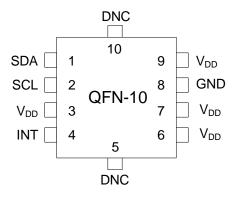
Reset value = 0000 0000

Bit	Name	Function
7:6	Reserved	
5		<ul> <li>When performing ALS-IR measurements, the ADC can be programmed to operate in high sensitivity operation or high signal range.</li> <li>The high signal range is useful in operation under direct sunlight.</li> <li>0: Normal Signal Range</li> <li>1: High Signal Range (Gain divided by 14.5)</li> </ul>
4:0	Reserved	Write operations to this RAM parameter must preserve this bit-field value using read-modify-write.



20°L

# 5. Pin Descriptions





	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$
Pin Name Ty	Table 13. Pin Descriptions     Type   Description
	rectional I <sup>2</sup> C Data.
2 SCL In	nput I <sup>2</sup> C Clock.
3 V <sub>DD</sub> Po	Power Supply. Voltage source.
4 INT Bidire	rectional Interrupt Output. Open-drain interrupt output pin. Must be at logic level high during power-up sequence to enable low power operation.
5 DNC	Do Not Connect. This pin is electrically connected to an internal Si1132 node. It should remain unconnected.
6 V <sub>DD</sub> Po	Power         Power Supply.           Voltage source.         Voltage source.
7 V <sub>DD</sub> Po	ower Power Supply. Voltage source.
	ower Ground. Reference voltage.
	Power Supply. Voltage source.
10 DNC	Do Not Connect. This pin is electrically connected to an internal Si1132 node. It should remain unconnected.



# 6. Ordering Guide

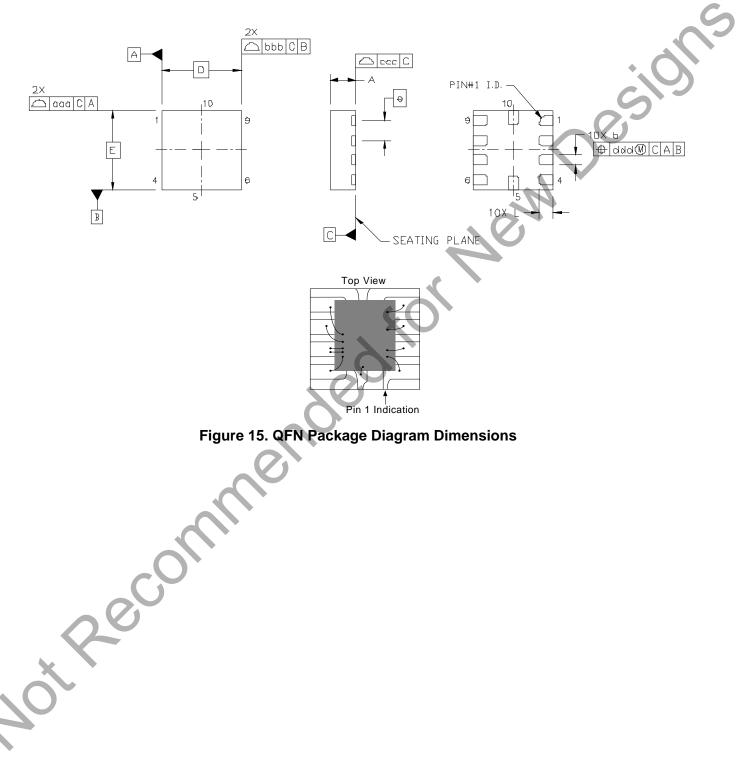
	Part Number	Package	
	Si1132-A10-GMR	QFN-10	
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# 7. Package Outline: 10-Pin QFN

Figure 15 illustrates the package details for the Si1132 QFN package. Table 14 lists the values for the dimensions shown in the illustration.





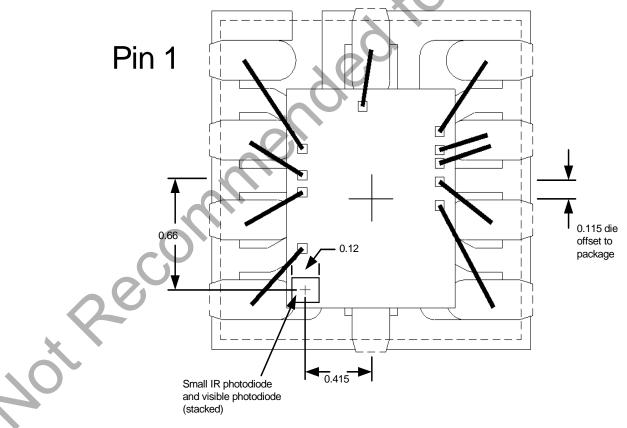
resign

6

	0	0			
Dimension	Min	Nom	Мах		
А	0.55	0.65	0.75		
b	0.20	0.25	0.30		
D		2.00 BSC.	·		
е	0.50 BSC.				
E	2.00 BSC.				
L	0.30	0.35	0.40		
aaa		0.10			
bbb		0.10			
CCC	0.08				
ddd	0.10				
Notes:		•			

Table 14. Package Diagram Dimensions

1. All dimensions shown are in millimeters (mm). 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

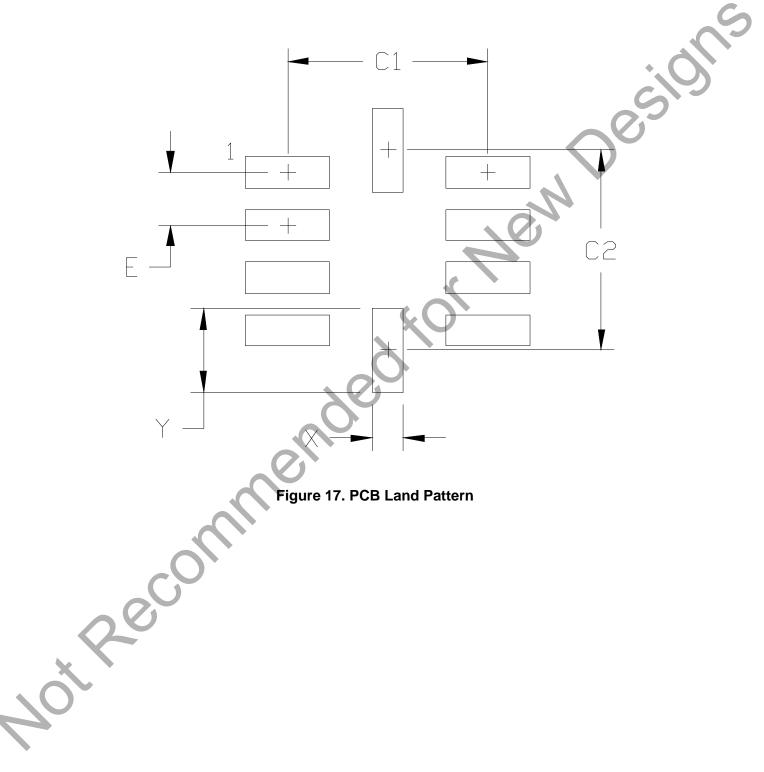


**Figure 16. Photodiode Centers** 



# 8. Suggested PCB Land Pattern

Figure 17 illustrates the PCB land pattern details for the Si1132. Table 15 lists the values for the dimensions shown in the illustration.





### Table 15. PCB Land Pattern Dimensions

Dimension	mm
C1	1.90
C2	1.90
E	0.50
Х	0.30
Y	0.80

#### Notes:

#### General

- 1. All dimensions shown are in millimeters (mm).
- 2. This Land Pattern Design is based on the IPC-7351 guidelines.
- All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

#### Solder Mask Design

4. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 mm minimum, all the way around the pad.

#### Stencil Design

- **5.** A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- 6. The stencil thickness should be 0.125 mm (5 mils).
- 7. The ratio of stencil aperture to land pad size should be 1:1 for all pads.

#### Card Assembly

eco

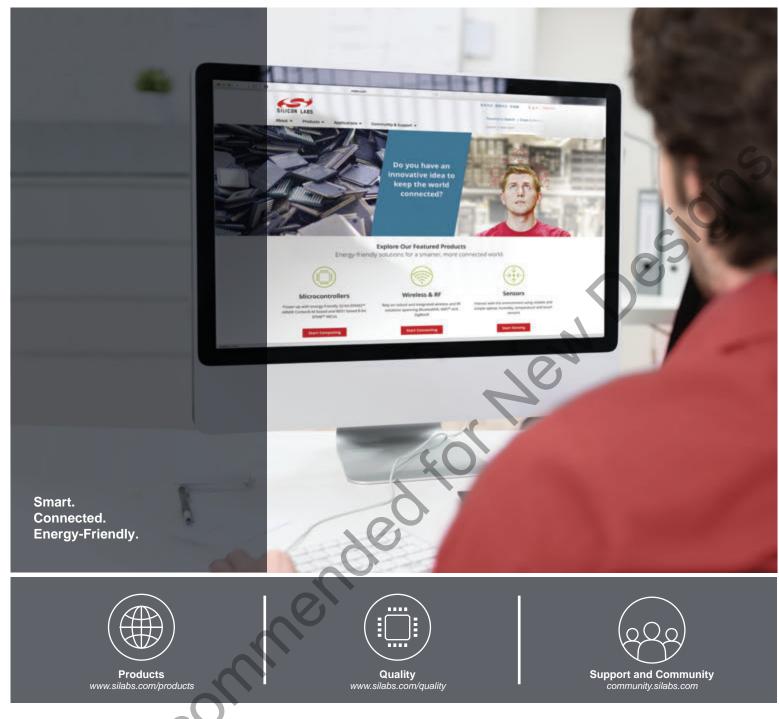
- **8.** A No-Clean, Type-3 solder paste is recommended.
- **9.** The recommended card reflow profile is per the JEDEC/IPC J-STD-020D specification for Small Body Components.



# **DOCUMENT CHANGE LIST**

- Not Recommended for New Designs





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